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ASX RELEASE **20 January 2026**

ASX: NVU

Upsized Strategic Placement Raises A$7.5 Million To Accelerate Commercialisation of ECS-DoT Chip

Funding received to support 16nm tape-out, live drone validation, and rollout of EMASS's commercial SoC platform

Highlights

- Firm commitments received to raise $7.5 million (before costs) via a Placement to new and existing sophisticated, professional and institutional investors at $0.088 per Share.
- Nanoveu's Directors to participate $120,000 in the Placement, subject to shareholder approval.
- Strengthened balance sheet positions Nanoveu for accelerated global expansion of EMASS's leading Edge-AI semiconductor technology, including its existing 22nm solution and next-generation 16nm ECS-DoT tape-out.
- Funds to support development and commercialisation of EMASS System-on-a-chip semiconductor technologies, EyeFly3D™, Nanoshield™ Solar coatings, and working capital.
- EMASS has delivered final GDS for the 16nm ECS-DoT system-on-chip into the TSMC/IMEC workflow, progressing through technical verification and bug-checking as part of the standard pathway toward light-mask preparation and tape-out readiness.
- The 16nm ECS-DoT has progressed from architecture to final GDS in approximately six months, materially faster than typical advanced-node SoC timelines.
- Live drone validation in collaboration with a specialist U.S drone firm advancing, with results expected later this quarter.[i]
- Testing designed to evaluate flight endurance improvements in real-world operating conditions, building on disruptive Phase 2 simulation results (300+ HIL campaigns) that exceeded 50% endurance improvements across all quadcopter, hexacopter and octocopter platforms.[i]

Nanoveu Limited (ASX: NVU, OTCQB: NNVUF) ("Nanoveu" or the "Company"), a technology innovator across advanced semiconductor and material sciences, is pleased to announce that it has received firm commitments to raise $7.5 million (before costs) through a placement of fully paid ordinary shares ("**Shares**") to new and existing sophisticated, professional, and institutional investors ("**Placement**").

The Placement will be conducted at an issue price of $0.088 per Share. Investors in the Placement will also receive 1 free attaching option for every 2 new Shares subscribed for and issued, exercisable at $0.15 on or before the date that is 3 years from the date the options are issued ("**Options**").

Nanoveu's Directors have committed to participate $120,000 in the Placement, subject to shareholder approval to be sought at an upcoming General Meeting.

Dr David Pevcic, Executive Chairman of NVU, commented: "*This funding allows us to scale and expand the commercial capability across Nanoveu and EMASS at a critical point in the ECS-DoT roadmap. Our immediate focus is on driving first design-ins from the existing 22nm ECS-DoT platform, while in parallel progressing our next-generation 16nm chip through to silicon. With manufacturing readiness and real-world validation now underway, we believe the Company is well positioned to convert technical momentum into major commercial outcomes.*"

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Funds from the Placement will be applied towards:

- EMASS Semiconductor: 16nm ECS-DoT tape out; live drone integration; commercialisation scale up activities; R&D activities;
- Corporate, administration and working capital; and
- EyeFly3D and nanocoating technologies.

From Design Execution to Commercial Scale

Since the acquisition of Embedded A.I. Systems Pte. Ltd. (EMASS), Nanoveu has rapidly advanced the research and development of EMASS's ECS-DoT edge-AI system-on-chip (SoC) platform. ECS-DoT is designed to execute AI inference directly on-device at milliwatt and sub-milliwatt power levels, reducing reliance on cloud connectivity and materially extending battery life. The EMASS ECS-DoT architecture combines highly compressed AI models, on-chip memory and an energy-efficient design to deliver meaningful AI performance within tight power and size constraints.

Importantly, this transition is now underpinned by two parallel validation streams:

- **Manufacturing-readiness**: EMASS has delivered the final 16nm ECS-DoT GDS into the TSMC/IMEC workflow, initiating standard technical verification, integrity checks, and bug analysis that progress the program along the pathway toward light-mask preparation and tape-out readiness. Completed in approximately six months from architecture to final GDS, this milestone transforms its next-generation SoC into a manufacturable silicon asset, strengthening customer engagement by shortening the pathway from demand to scalable production.
- **Application validation**: In parallel, EMASS is progressing a structured drone evaluation program advancing from simulation into live flight validation in collaboration with a specialist U.S. drone firm. Phase 2 simulation campaigns (300+ HIL runs) reported endurance gains consistently exceeding the 50% threshold across platforms, with headline gains of up to 80% (quadcopter), up to 75% (hexacopter under payload stress), and up to 85% (octocopter), achieved without changes to batteries, propulsion, or airframes. The live program is designed to confirm that these endurance improvements and control-loop performance translate under real-world variability, generating mission-relevant evidence to support OEM and system integrator engagement as results are received.

Momentum is further building around the ECS-DoT platform, supported by:

- **Strategic U.S. collaborations with Arrow Electronics and Semtech**, supporting accelerated go-to-market execution through global distribution, engineering support, reference designs and the integration of ECS-DoT with long-range, low-power LoRa® connectivity for industrial and infrastructure applications.
- **The establishment of U.S. and European sales teams** to broaden access to major electronics markets and customers.

Details of the Placement

Under the Placement the Company will issue a total of 85,227,274 Shares and 42,613,637 free attaching Options. 83,863,637 Shares at an issue price of $0.088 per Share with 41,931,818 free attaching Options will be issued under the Company's existing ASX Listing Rule 7.1 and 7.1A placement capacities. The remaining 1,363,637 Shares and 681,819 free attaching Options to be issued to the Directors are subject to shareholder approval.

The offer price of $0.088 per new share represents a:

- 9.28% discount to the last traded price of $0.097 per share on 15 January 2026, being the last date that the Company's shares traded on the ASX prior to the date of this announcement;
- 7.41% discount to the 10-day volume weighted average price ("VWAP") price of $0.095 per share up to and including 15 January 2026,
- 5.96% discount to the 15-day VWAP of $0.0936 per share up to and including 15 January 2026; and
- 4.84% discount to the 20-day VWAP of $0.0925 per share up to and including 15 January 2026.

The Placement was jointly led by Evolution Capital and 62 Capital ("Joint Lead Managers"). The Joint Lead Managers will receive a fee of 6% of the gross amount raised, together with 15,000,000 unlisted Options on the same terms as the Placement options (exe $0.15, exp 3 years).

The Placement will be completed within Nanoveu's existing ASX Listing Rule 7.1 and 7.1A placement capacities. Settlement of the New Shares and Options is expected to occur on or around 27 January 2026, with the Director Participation anticipated to be completed shortly after.

This announcement has been authorised for release by the Board of Directors.

-ENDS-

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About Nanoveu Limited

Further details on the Company can be found at https://nanoveu.com/.

EMASS is a pioneering technology company specialising in the design and development of advanced systems-on-chip (SoC) solutions. These SoCs enable ultra-low-power, AI-driven processing for smart devices, IoT applications, and 3D content transformation. With its industry-leading technology, EMASS will enhance Nanoveu's portfolio, empowering a wide range of industries with efficient, scalable AI capabilities, further positioning Nanoveu as a key player in the rapidly growing 3D content, AI and edge computing markets.

EyeFly3D™ is a comprehensive platform solution for delivering glasses-free 3D experiences across a range of devices and industries. At its core, EyeFly3D™ combines advanced screen technology, sophisticated software for content processing, and now, with the integration of EMASS's ultra-low-power SoC, powerful hardware.

Nanoshield™ is a self-disinfecting film that uses a patented polymer of embedded Cuprous nanoparticles to provide antiviral and antimicrobial protection for a range of applications, from mobile covers to industrial surfaces. Applications include, *Nanoshield™ Marine*, which prevents the growth of aquatic organisms on submerged surfaces like ship hulls, and *Nanoshield™ Solar*, designed to prevent surface debris on solar panels, thereby maintaining optimal power output.

Forward Looking Statements This announcement contains 'forward-looking information' that is based on the Company's expectations, estimates and projections as of the date on which the statements were made. This forward-looking information includes, among other things, statements with respect to the Company's business strategy, plans, development, objectives, performance, outlook, growth, cash flow, projections, targets and expectations and related expenses. Generally, this forward-looking information can be identified by the use of forward-looking terminology such as 'outlook', 'ambition', 'anticipate', 'project', 'target', 'potential', 'likely', 'believe', 'estimate', 'expect', 'intend', 'may', 'mission', 'would', 'could', 'should', 'scheduled', 'will', 'plan', 'forecast', 'evolve' and similar expressions. Persons reading this announcement are cautioned that such statements are only predictions, and that the Company's actual future results or performance may be materially different. Forward-looking information is subject to known and unknown risks, uncertainties and other factors that may cause the Company's actual results, level of activity, performance, or achievements to be materially different from those expressed or implied by such forward looking information.

[i] Refer ASX Quarterly Activities and Appendix 4C Cash Flow Reports dated 31 October 2025.

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